L Number	Hits	Search Text	DB	Time stamp
1	6	((((257/635,700,758).CCLS.) or	USPAT;	2003/04/11 08:40
¥		((257/211,266,324).CCLS.)) and ((first adj	US-PGPUB;	
		wiring and second adj wiring) near layer))	EPO; JPO;	
	:	and electrode and (multi-chip or multichip	DERWENT; IBM TDB	
2	2	or multi near chip) ("6274404").PN.	USPAT;	2003/04/11 08:01
-	2	\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
_	_		IBM_TDB	00000404411 00 01
3	2	("6403463").PN.	USPAT;	2003/04/11 08:01
;			US-PGPUB; EPO; JPO;	
			DERWENT;	
ļ !			IBM TDB	1
4	1	((first adj wiring and second adj wiring)	USPAT;	2003/04/11 08:44
		near layer) and electrode and (multi-chip	US-PGPUB;	
j		or multichip or multi near chip) and	EPO; JPO;	
		conductive with bus	DERWENT;	
6	^	(((first adj wiring and second adj wiring)	IBM_TDB USPAT;	2003/04/11 08:44
	U	near layer) and electrode and (multi-chip	US-PGPUB;	2003/03/TT 00'44
		or multichip or multi near chip) and	EPO; JPO;	
	i	conductive near5 bus) not ((first adj	DERWENT;	
	į	wiring and second adj wiring) near layer)	IBM_TDB	•
		and electrode and (multi-chip or multichip		Taranta e e
		or multi near chip) and conductive with		
5	1	bus) ((first adj wiring and second adj wiring)	USPAT;	2003/04/11 09:17
)	T	near layer) and electrode and (multi-chip	US-PGPUB;	2003/04/11 03.1/
(7		or multichip or multi near chip) and	EPO; JPO;	
		conductive near5 bus	DERWENT;	
			IBM_TDB	
7	16	electrode and (multi-chip or multichip or	USPAT;	2003/04/11 09:17
		multi near chip) and conductive near5 bus	US-PGPUB; EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	3648	(257/635,700,758).CCLS.	USPAT;	2003/04/10 14:56
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	i 1 1
_	1271	(257/211,266,324).CCLS.	IBM_TDB USPAT;	2003/04/10 12:53
1.4	1214	(201/211,200,321,0000.	US-PGPUB;	2000/01/10 12.00
			EPO; JPO;	
		·	DERWENT;	
	00:5	(420 (110 (600) 607 6	IBM_TDB	0000/04/10 10 50
-	2641	(438/118,622).CCLS.	USPAT;	2003/04/10 12:53
			US-PGPUB; EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	3086	(438/128,129,216,261,591,593).CCLS.	USPĀT;	2003/04/10 12:54
			US-PGPUB;	
		-	EPO; JPO;	
			DERWENT; IBM TDB	
_	4	'multiple-chip' and	USPAT;	2003/04/10 12:57
	7	((257/635,700,758).CCLS.)	US-PGPUB;	
1			EPO; JPO;	
			DERWENT;	
# # # # # # # # # # # # # # # # # # #			IBM_TDB	0000/01/10 15 55
-	0	'multiple-chip' and	USPAT;	2003/04/10 12:57
		((257/211,266,324).CCLS.)	US-PGPUB; EPO; JPO;	
			DERWENT;	
	į		IBM TDB	
				<u> </u>

<b>–</b>	***************************************	0	'multiple-chip' and ((438/118,622).CCLS.)	USPAT;	2003/04/10 12:57
				US-PGPUB;	
				EPO; JPO; DERWENT;	
<u></u>				IBM TDB	
-		0	'multiple-chip' and	USPAT;	2003/04/10 12:57
			((438/128,129,216,261,591,593).CCLS.)	US-PGPUB;	
				EPO; JPO; DERWENT;	
				IBM_TDB	1
_	An anni-rate state.	224	'multiple-chip'	USPĀT;	2003/04/10 14:10
4				US-PGPUB; EPO; JPO;	
				DERWENT;	
				IBM_TDB	
-		1444	stack\$3 near chip	USPAT;	2003/04/10 14:11
				US-PGPUB; EPO; JPO;	
				DERWENT;	
	And the state of t			IBM_TDB	
<b>–</b>		22	(stack\$3 near chip) and ((257/635,700,758).CCLS.)	USPAT; US-PGPUB;	2003/04/10 14:12
			((2377033,700,730).ССВЗ.)	EPO; JPO;	
				DERWENT;	
		2	/	IBM_TDB	2002/04/10 14 22
_	:	2	(stack\$3 near chip) and ((257/211,266,324).CCLS.)	USPAT; US-PGPUB;	2003/04/10 14:32
			((201/211/200/021/100001/	EPO; JPO;	
				DERWENT;	
		3	(atack\$2 near chin) and	IBM_TDB USPAT;	2003/04/10 14:33
-		3	(stack\$3 near chip) and ((438/128,129,216,261,591,593).CCLS.)	US-PGPUB;	2003/04/10 14:33
			((100, 100, 100, 100, 100, 100, 100, 100	EPO; JPO;	
	1			DERWENT;	
		32	(stack\$3 near chip) and	IBM_TDB USPAT;	2003/04/10 14:55
-		32	((438/118,622).CCLS.)	US-PGPUB;	2003/04/10 14:33
				EPO; JPO;	
				DERWENT;	
_		3648	(257/635,700,758).CCLS.	IBM_TDB USPAT;	2003/04/10 14:56
		3313	(2017,000,100,100,100,100,100,100,100,100,	US-PGPUB;	2003,01,10 11.00
				EPO; JPO;	
				DERWENT; IBM TDB	
_		2	("5892276").PN.	USPAT;	2003/04/10 14:59
				US-PGPUB;	
				EPO; JPO;	
	Ì			DERWENT; IBM TDB	
_		2	("5939790").PN.	USPAT;	2003/04/10 15:27
				US-PGPUB;	
				EPO; JPO; DERWENT;	
				IBM TDB	
-		130		USPĀT;	2003/04/10 16:08
			((257/211,266,324).CCLS.)	US-PGPUB;	
				EPO; JPO; DERWENT;	
	L-y stiller value			IBM_TDB	
_		4792	((257/635,700,758).CCLS.) or	USPĀT;	2003/04/10 16:08
			((257/211,266,324).CCLS.)	US-PGPUB; EPO; JPO;	
				DERWENT;	
		_		IBM_TDB	
_		888	(((257/635,700,758).CCLS.) or	USPAT;	2003/04/10 16:09
			((257/211,266,324).CCLS.)) and ('multi-chip' chips (stack\$3 near chip))	US-PGPUB; EPO; JPO;	·
	Anne and the fermions		,	DERWENT;	!
				IBM TDB	

_	5355	first adj wiring and second adj wiring	USPAT;	2003/04/10 16:10
1	f }		US-PGPUB;	•
	-		EPO; JPO;	
1	<u></u>		DERWENT;	
			IBM TDB	;
_	2275	(first adj wiring and second adj wiring)	USPĀT;	2003/04/10 16:11
		near layer	US-PGPUB;	
			EPO; JPO;	
1			DERWENT;	
!	141		IBM TDB	
-	189	(((257/635,700,758).CCLS.) or	USPAT;	2003/04/10 16:11
F.49		((257/211,266,324).CCLS.)) and ((first adj	US-PGPUB;	:
	1	wiring and second adj wiring) near layer)	EPO; JPO;	, ,
			DERWENT;	
1			IBM_TDB	a contract of the contract of
_	98	((((257/635,700,758).CCLS.) or	USPAT;	2003/04/11 07:29
}		((257/211,266,324).CCLS.)) and ((first adj	US-PGPUB;	
		wiring and second adj wiring) near layer))	EPO; JPO;	
		and electrode	DERWENT;	
			IBM TDB	

Page 3